



Making Connections:

The XLYNX Materials Newsletter

November 2025

Commercial Green Light & Advanced Patterning Breakthrough

At XLYNX Materials, our mission is to provide the next generation of high-performance, sustainable chemistry that solves the microelectronics industry's most persistent material trade-offs. We are excited to announce two major milestones this quarter that directly accelerate the commercial adoption and technical versatility of our advanced reagents, particularly the BondLynx™ family of crosslinkers.



XLYNX Reagents Receive EPA Low-Volume Exemption

We're please to share that we've recently received a low-volume exemption approval (LVE) from the US EPA for a select category of our advanced reagents. This exemption allows us to further support our customers for commercial applications of these products in the US. We're excited about the possibility this opens up and look forward to continuing to meet the needs of our partners.



Expanding the Performance Envelope

Patterning of Conductive Polymers

Approximately six months ago, XLYNX Materials' focus was primarily concentrated on developing crosslinking solutions for the broader Coatings, Adhesives, Sealants, and Elastomers (CASE) markets. While our successes there continue, we have made significant internal progress in applying our unique C-H insertion chemistry to the highly specialized field of microelectronics fabrication.

This progress culminated in a major internal R&D breakthrough: **successful direct photopatterning of a non-photosensitive conductive polymer on an unmodified silicon wafer.**

The Technical Achievement (Using BXW-202):

The ability to directly pattern functional materials (like conductive polymers) onto common semiconductor substrates is a key step toward enabling next-generation printed and flexible electronics.

Our team used our core crosslinking reagent, **BXW-202**, to photosensitize a polymer that inherently lacked any functional groups for lithography. This process bypasses the complex pre-functionalization steps typically required in formulation and demonstrates the unique versatility of our technology.

The Implications for Microelectronics:

- **Enabling New Conductive Materials:** This success proves that BondLynx™ can transform materials previously confined to basic coating applications into lithographically capable layers. It offers a new pathway for formulating complex devices like flexible circuits and

sensors using novel **conductive inks** and materials.

- **Simplified Manufacturing:** By achieving direct patterning on an unmodified wafer, we eliminate intermediate steps (like surface plasma treatments or dedicated adhesion layers). This simplification is critical for improving yield and reducing manufacturing costs in high-volume production of advanced microdevices.

This breakthrough affirms that our core chemistry provides the robust foundation needed not only to solve traditional material performance trade-offs but also to fundamentally simplify and expand the manufacturing toolkit for the flexible and printed electronics industry.

For questions, pricing and trial information

Contact Us

Missed an edition of *Making Connections*?

The newsletter archive is now available on our website. Check out what you missed!

[Newsletter Archive](#)

We're Here to Help

What adhesion, stabilization or photopatterning challenge is your business facing?

Let's talk.

Our platform of diazirine crosslinking technology is proven to improve performance across a wide range of applications, and can be customized for specific material substrates.

To learn more, contact us at any time:

info@xlynxmaterials.com

Thanks for the read, see you next month!



XLYNX Materials Inc.

965 Alston Street

Victoria, British Columbia

Canada



info@xlynxmaterials.com

You received this email because you signed up on our website or have spoken with us recently.

[Unsubscribe](#)